

Title (en)

CARRIER, HOLDER, LASER CUTTING DEVICE AND METHOD FOR SEPARATING SEMICONDUCTOR PRODUCTS USING LASER LIGHT

Title (de)

TRÄGER, HALTER, LASERSCHNEIDEINRICHTUNG UND VERFAHREN ZUM TRENNEN VON HALBLEITERPRODUKTEN MIT LASERLICHT

Title (fr)

PLAQUE DE SUPPORT, DISPOSITIF DE SUPPORT, DISPOSITIF DE DECOUPAGE AU LASER, ET PROCEDE PERMETTANT DE SEPARER DES PRODUITS A SEMICONDUCTEURS AU MOYEN D'UN LUMIERE LASER

Publication

**EP 1588405 A2 20051026 (EN)**

Application

**EP 04703293 A 20040119**

Priority

- NL 2004000040 W 20040119
- NL 1022463 A 20030122

Abstract (en)

[origin: WO2004066369A2] The invention relates to a carrier and to a holder for supporting and engaging semiconductor products during separating of the products using laser light. The invention also relates to a method for supporting and engaging semiconductor products during separating of the products using laser light.

IPC 1-7

**H01L 21/00**

IPC 8 full level

**H01L 21/00** (2006.01); **H01L 21/683** (2006.01)

CPC (source: EP KR US)

**H01L 21/67092** (2013.01 - EP US); **H01L 21/68** (2013.01 - KR); **H01L 21/6838** (2013.01 - EP US)

Citation (search report)

See references of WO 2004066369A2

Designated contracting state (EPC)

DE GB IT NL

DOCDB simple family (publication)

**WO 2004066369 A2 20040805**; **WO 2004066369 A3 20040930**; CN 1742359 A 20060301; EP 1588405 A2 20051026; JP 2006517730 A 20060727; KR 20050099506 A 20051013; NL 1022463 C2 20040726; TW 200417101 A 20040901; US 2006231454 A1 20061019

DOCDB simple family (application)

**NL 2004000040 W 20040119**; CN 200480002669 A 20040119; EP 04703293 A 20040119; JP 2006500732 A 20040119; KR 20057013533 A 20050722; NL 1022463 A 20030122; TW 93101505 A 20040120; US 54221304 A 20040119